

What is claimed is:

1. A substrate for a semiconductor device, having a mounting region for a semiconductor chip, wherein at least one hole is formed at a position where cutting lines intersect.

2. The substrate for a semiconductor device as defined in claim 1,

wherein one of the holes is formed at the position where the cutting lines intersect; and

wherein the hole is formed to a size that comprises an intersection portion of the cutting lines.

3. The substrate for a semiconductor device as defined in claim 1,

wherein a plurality of the holes are formed at the position where cutting lines intersect; and

wherein part of each of the holes is superimposed on an intersection portion between the cutting lines.

4. The substrate for a semiconductor device as defined in claim 3,

wherein the plurality of holes are positioned on edges of one of the cutting lines that is to be cut last, in the intersection portion.

5. The substrate for a semiconductor device as defined in

claim 4,

wherein the plurality of holes are formed on part of the cutting line that is to be cut last, when that part is to be cut earlier than the intersection portion between the cutting lines.

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6. The substrate for a semiconductor device as defined in claim 4,

wherein the plurality of holes are formed on part of the cutting line that is to be cut last, when that part is to be cut after the intersection portion between the cutting lines.

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7. The substrate for a semiconductor device as defined in claim 4,

wherein the spacing between one of the holes formed on an edge of the cutting line that is to be cut last and another of the holes formed on another edge of the cutting line is less than the thickness of a cutting portion of a cutting tool.

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8. The substrate for a semiconductor device as defined in claim 1,

wherein at least one of the holes is formed; and

wherein the hole has an aperture portion that is closed by a cover.

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9. The substrate for a semiconductor device as defined in claim 8,

wherein an interconnecting pattern is formed; and
wherein the cover is formed of the same material as the
interconnecting pattern.

5 10. A semiconductor chip mounting substrate comprising:
a substrate of a material that can be cut into separate
pieces, in which is formed at least one hole at an intersection
portion between cutting lines for separating the substrate into
a plurality of individual products; and

10 10 a plurality of semiconductor chips which are mounted on
the substrate.

11. The semiconductor chip mounting substrate as defined in
claim 10,

15 15 wherein the plurality of semiconductor chips are sealed
in by resin.

12. The semiconductor chip mounting substrate as defined in
claim 11, wherein the resin fills the hole.

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13. The semiconductor chip mounting substrate as defined in
claim 10,

wherein the hole is formed to a size that comprises the
intersection portion of the cutting lines.

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14. The semiconductor chip mounting substrate as defined in
claim 11,

wherein the hole has an aperture portion that is closed by a cover; and

wherein the resin is provided on a surface of the substrate on which the cover is provided.

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15. A semiconductor device comprising:

a semiconductor chip;

a substrate on which the semiconductor chip is mounted and which is formed by cutting apart a larger substrate; and

resin for sealing the semiconductor chip;

wherein the semiconductor device has an outer shape having a corner portion; and

wherein a part of the substrate is indented further inward than an edge surface of the resin at the corner portion.

15 16. The semiconductor device as defined in claim 15,

wherein the substrate at the corner portion forms a shape that is indented in the opposite direction from the direction in which the corner portion protrudes, and thus an edge surface 20 of the substrate is indented further inward than the edge surface of the resin.

25 17. The semiconductor device as defined in claim 15,

wherein the formation of a thinner portion in the substrate at the corner portion ensures that a surface of the thinner portion of the substrate is indented further inward than the edge surface of the resin.

18. The semiconductor device as defined in claim 15,
wherein the part of the substrate that is indented further
inward than the edge surface of the resin at the corner portion
5 is covered by the resin.

19. The semiconductor device as defined in claim 15,
wherein a cover is provided at the corner portion, between
the substrate and the resin; and

10 wherein the part of the substrate that is indented further
inward than the edge surface of the resin is exposed.

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15 20. A circuit board on which is mounted the semiconductor
device as defined in claim 15.

21. Electronic equipment provided with the semiconductor
device as defined in claim 15.

20 22. A method of fabricating a semiconductor device, the
method comprising:

a first step of mounting a plurality of semiconductor
chips on a substrate on which is formed at least one hole at
a position where cutting lines intersect, then sealing the
plurality of semiconductor chips with resin; and

25 a second step of cutting the substrate and the resin into
individual products along the cutting lines, through at least
part of the hole.

23. The method of fabricating a semiconductor device as defined in claim 22,

wherein the resin fills the hole in the first step.

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24. The method of fabricating a semiconductor device as defined in claim 22,

wherein at least one of the holes is formed in the substrate;

10 wherein a cover is provided to block the hole, before the first step; and

wherein flow of the resin into the hole during the first step is prevented by the cover.

15 25. The method of fabricating a semiconductor device as defined in claim 24, further comprising a step of forming an interconnecting pattern in the substrate, before the first step;

20 wherein the cover is formed during the step of forming the interconnecting pattern.

26. The method of fabricating a semiconductor device as defined in claim 22,

25 wherein one of the holes is formed at the position where the cutting lines intersect; and

wherein the substrate and the resin are cut through an inner side of the hole in the second step.

27. The method of fabricating a semiconductor device as defined in claim 22,

5 wherein a plurality of the holes are formed at the position where the cutting lines intersect;

wherein the plurality of holes are positioned on edges of one of the cutting lines that is to be cut last, at the position where the cutting lines intersect; and

10 wherein the substrate and the resin are cut through part of each of the holes in the second step.

28. The method of fabricating a semiconductor device as defined in claim 27,

15 wherein the substrate and the resin are cut by a cutting tool having a thickness that is greater than the spacing between one of the holes formed on an edge of the cutting line that is to be cut last and another of the holes formed on another edge of the cutting line.